

FIG. 1

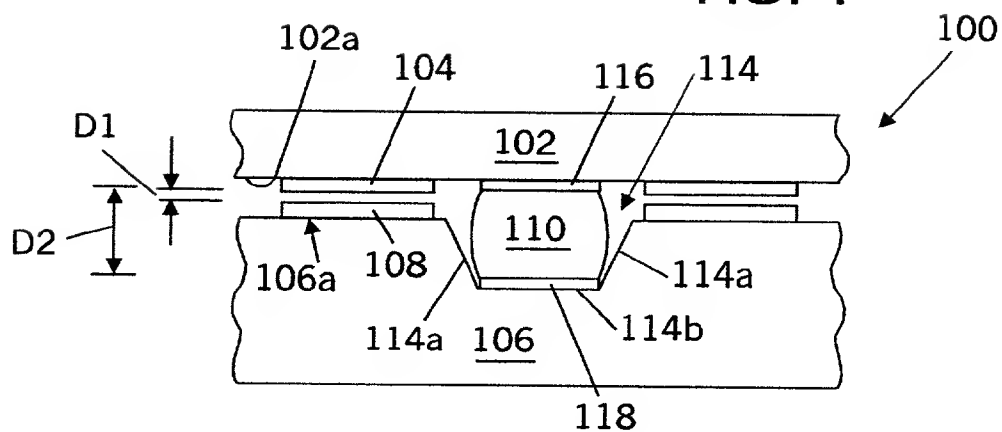


FIG. 2

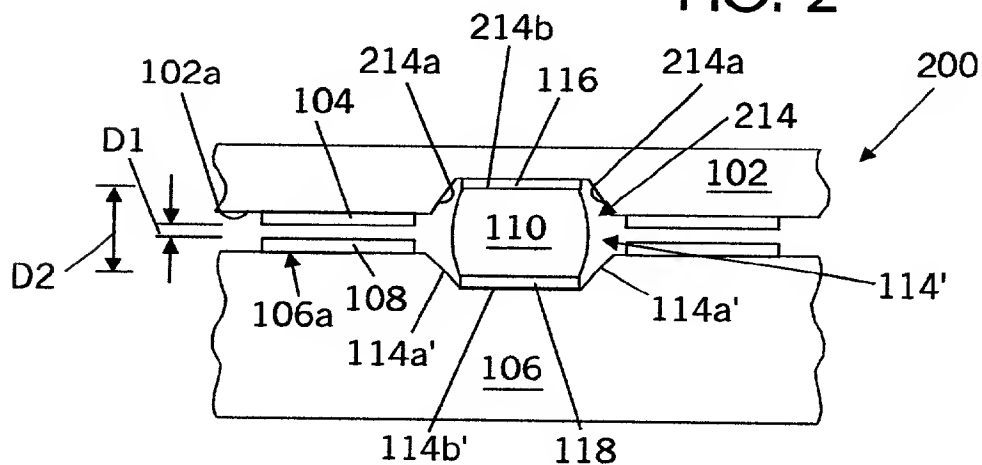


FIG. 3

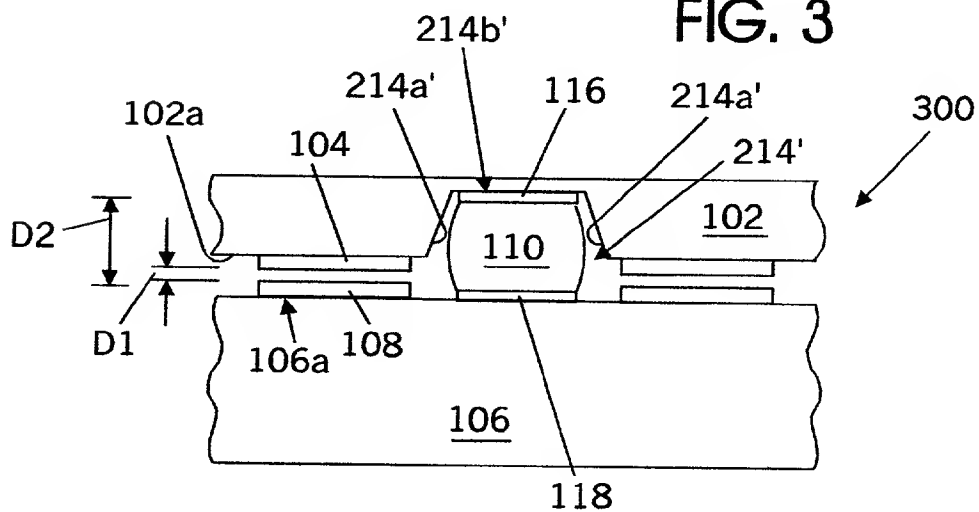


FIG. 4

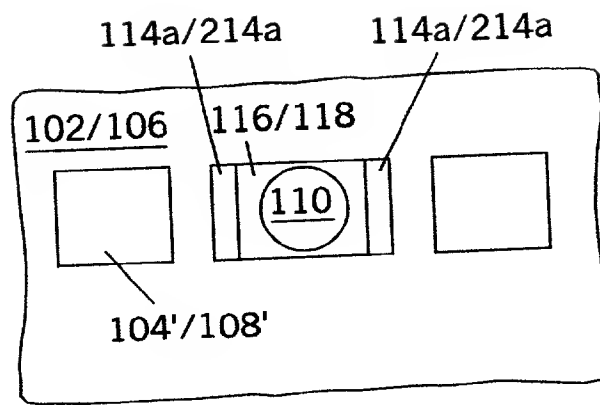


FIG. 5

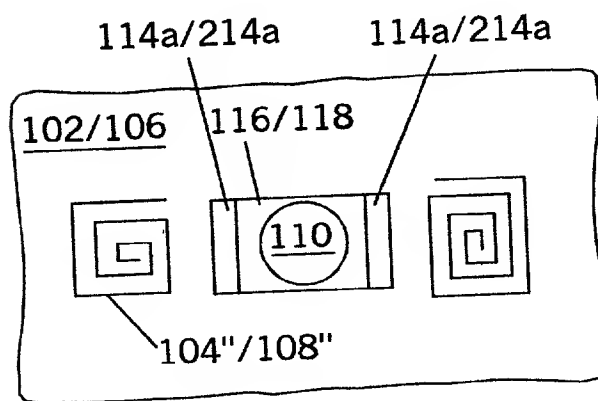


FIG. 6

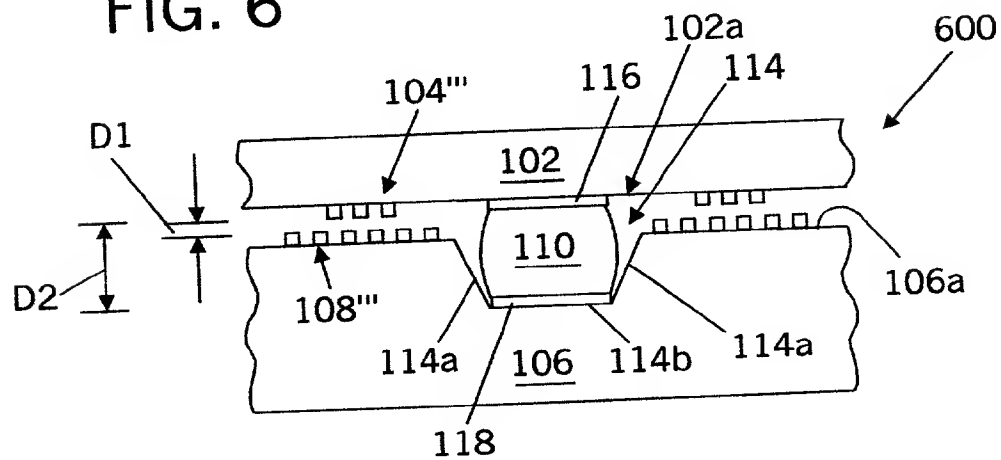


FIG. 7

FIG. 7 is a cross-sectional view of a device 700. The device includes a substrate 106 with a central opening 110. A layer 102 is disposed on the substrate, with a central portion 116 and side portions 114. A layer 104 is disposed on top of the side portions 114. A layer 108 is disposed on the substrate 106, with a central portion 114a and side portions 114b. A layer 106a is disposed on top of the side portions 114b. A layer 740 is disposed on top of the central portion 116. A layer 730 is disposed on top of the side portions 114a. Dimensions D1 and D2 are indicated. Arrows point to various components.

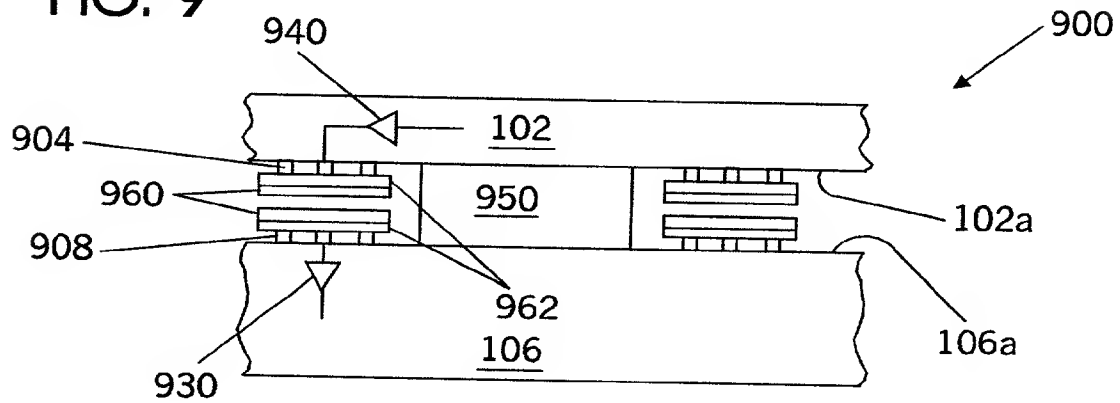
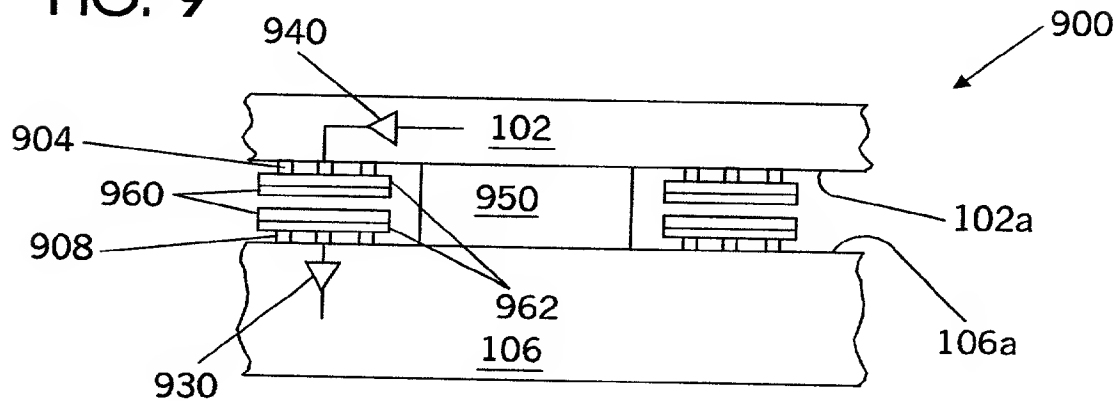
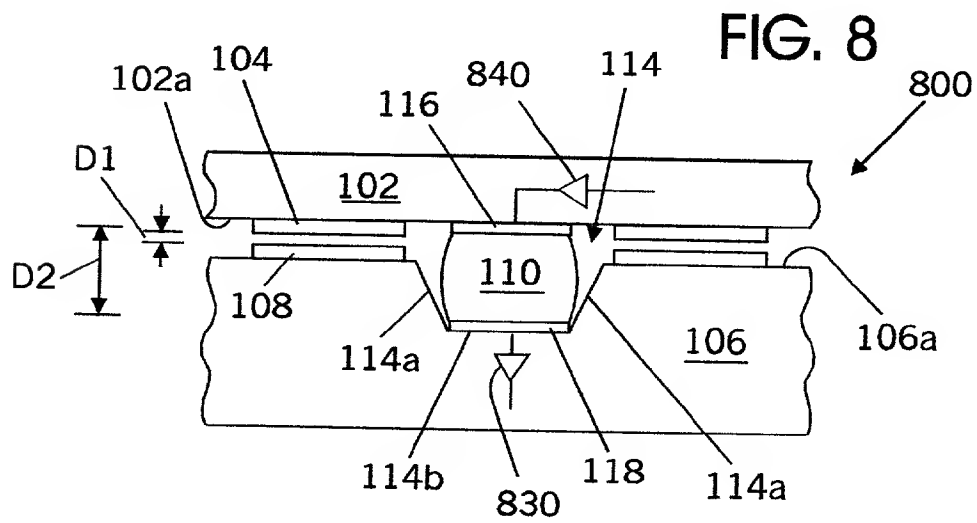


FIG. 10

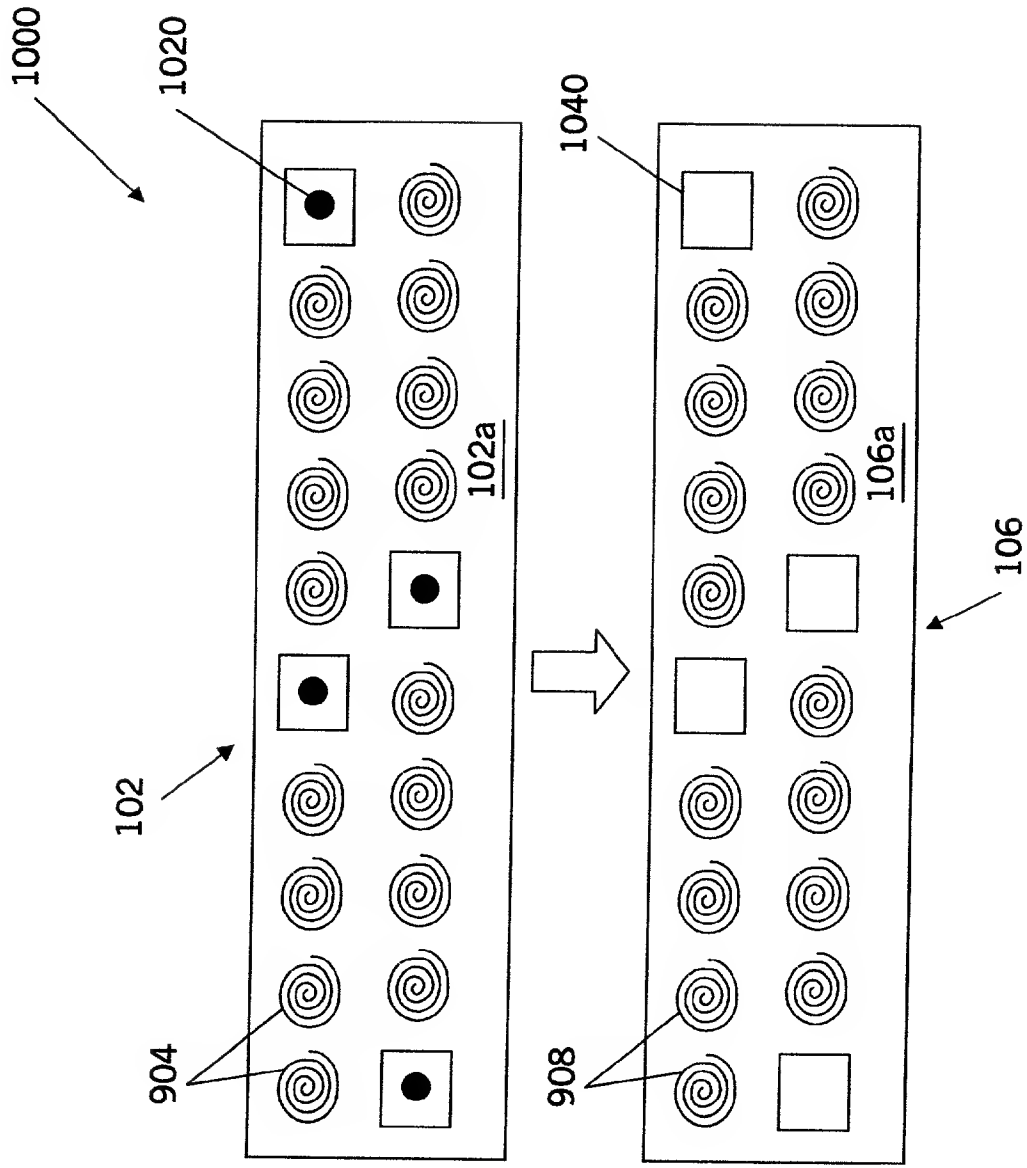


FIG. 11

